TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSV)

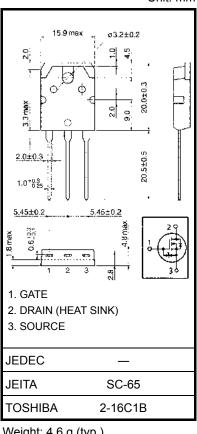
2SK2699

Chopper Regulator, DC-DC Converter and Motor Drive Applications

- Low drain-source ON resistance $: RDS (ON) = 0.5 \Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 11 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 600 \ V)$
- Enhancement mode $: V_{th} = 2.0 \sim 4.0 V (V_{DS} = 10 V, I_{D} = 1 mA)$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	600	V
Drain-gate voltage (R	_{GS} = 20 kΩ)	V _{DGR}	600	V
Gate-source voltage		V _{GSS}	±30	V
Drain current	DC (Note 1)	۱ _D	12	А
	Pulse (Note 1)	I _{DP}	48	А
Drain power dissipation	n (Tc = 25°C)	PD	150	W
Single pulse avalanche energy (Note 2)		E _{AS}	605	mJ
Avalanche current		I _{AR}	12	А
Repetitive avalanche energy (Note 3)		E _{AR}	15	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C



Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch−c)}	0.833	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	50	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 7.35 mH, R_G = 25 Ω , I_{AR} = 12 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Electrical Characteristics (Ta = 25°C)

Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V_{GS} = ±25 V, V_{DS} = 0 V	_	_	±10	μA
Gate-source br	eakdown voltage	V _(BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V		_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	-	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 6 A	_	0.5	0.65	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 6 A	6.0	11.0	_	S
Input capacitance	ce	C _{iss}			2600	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		270		pF
Output capacitance		C _{oss}			820		
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \int_{U} \stackrel{I_{D}=6A}{}_{R_{L}=50\Omega} V_{out}$	_	45	_	
	Turn-on time	t _{on}		_	75	_	
	Fall time	t _f		_	65	_	- ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, t _w =10µs		270		
Total gate charge (gate-source plus gate-drain)		Qg		_	58	_	
Gate-source charge		Q _{gs}	V _{DD} ≈ 480 V, V _{GS} = 10 V, I _D = 12 A		37	_	nC
Gate-drain ("miller") Charge		Q _{gd}			21	_	

Source–Drain Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	12	А
Pulse drain reverse current (Note 1)	I _{DRP}	_		_	48	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 12 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 12 A, V _{GS} = 0 V		460		ns
Reverse recovery charge	Qrr	dI _{DR} / dt = 100 A / µs		4.8		μC

Marking

